

- [54] **HEAT-SINK FOR ELECTRONIC SEMICONDUCTOR DEVICES**
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- [73] **Assignee: Aavid Engineering, Inc., Laconia, N.H.**
- [\*\*] **Term: 14 Years**
- [21] **Appl. No.: 208,924**
- [22] **Filed: Nov. 21, 1980**
- [51] **Int. Cl. .... D13-03**
- [52] **U.S. Cl. .... D13/23**
- [58] **Field of Search ..... 357/81; 165/80 R, 80 A, 165/80 B; D13/23; 174/16 HS**

- [56] **References Cited**  
**U.S. PATENT DOCUMENTS**  
3,893,161 7/1975 Pesak, Jr. .... 357/81  
4,012,769 3/1977 Edwards et al. .... 174/16 HS X

*Primary Examiner*—Susan J. Lucas

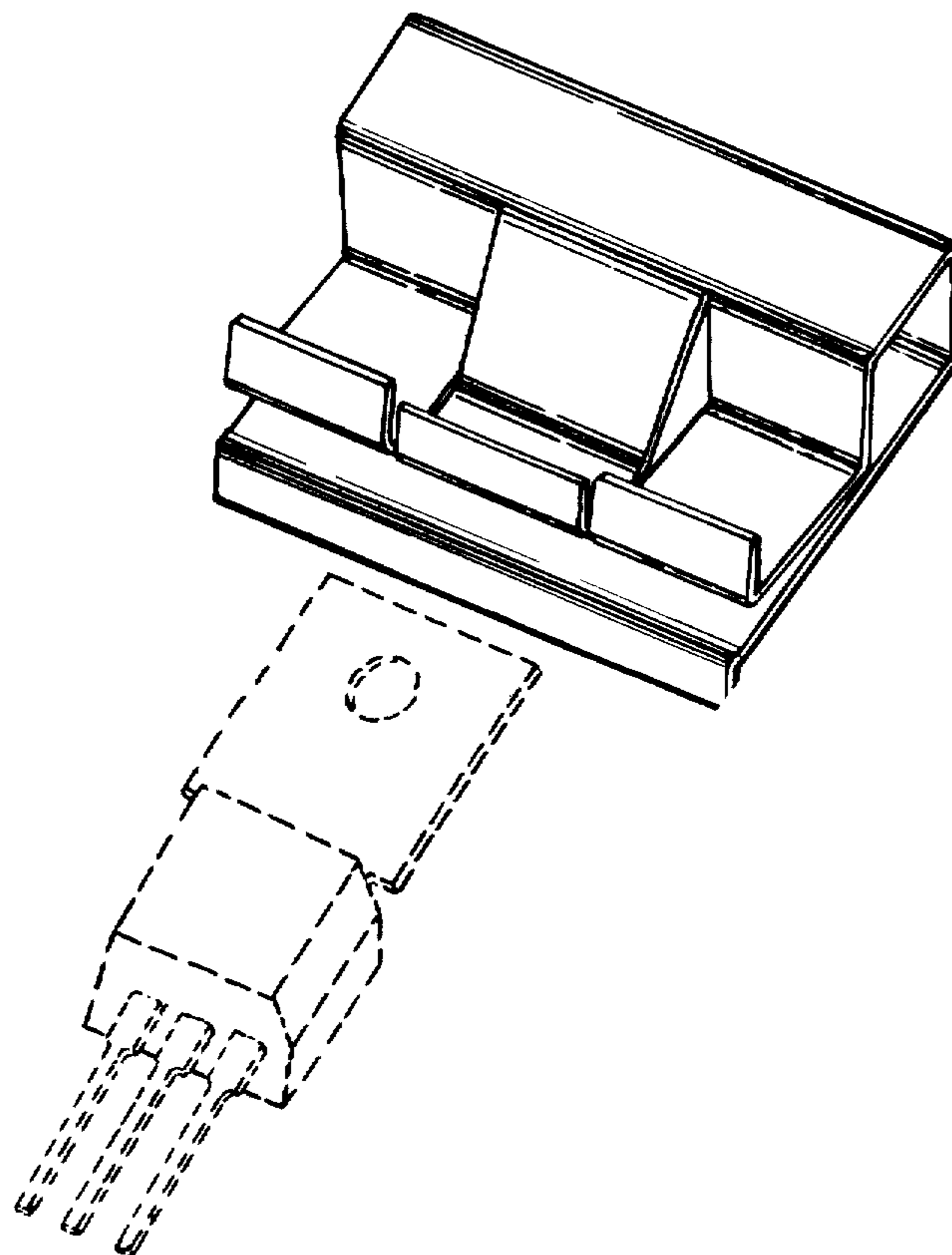
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[57] **CLAIM**

The ornamental design for a heat-sink for electronic semiconductor devices, substantially as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a heat sink for electronic semiconductor devices showing my new design, the semiconductor being shown in broken lines for illustrative purposes only;  
FIG. 2 is a front elevational view thereof;  
FIG. 3 is a rear elevational view thereof;  
FIG. 4 is a side elevational view thereof, looking toward the right side of the heat-sink as it is shown in FIG. 1;  
FIG. 5 is a side elevational view thereof, looking toward the left side of the heat-sink as it is shown in FIG. 1;  
FIG. 6 is a top plan view thereof; and  
FIG. 7 is a bottom plan view thereof.



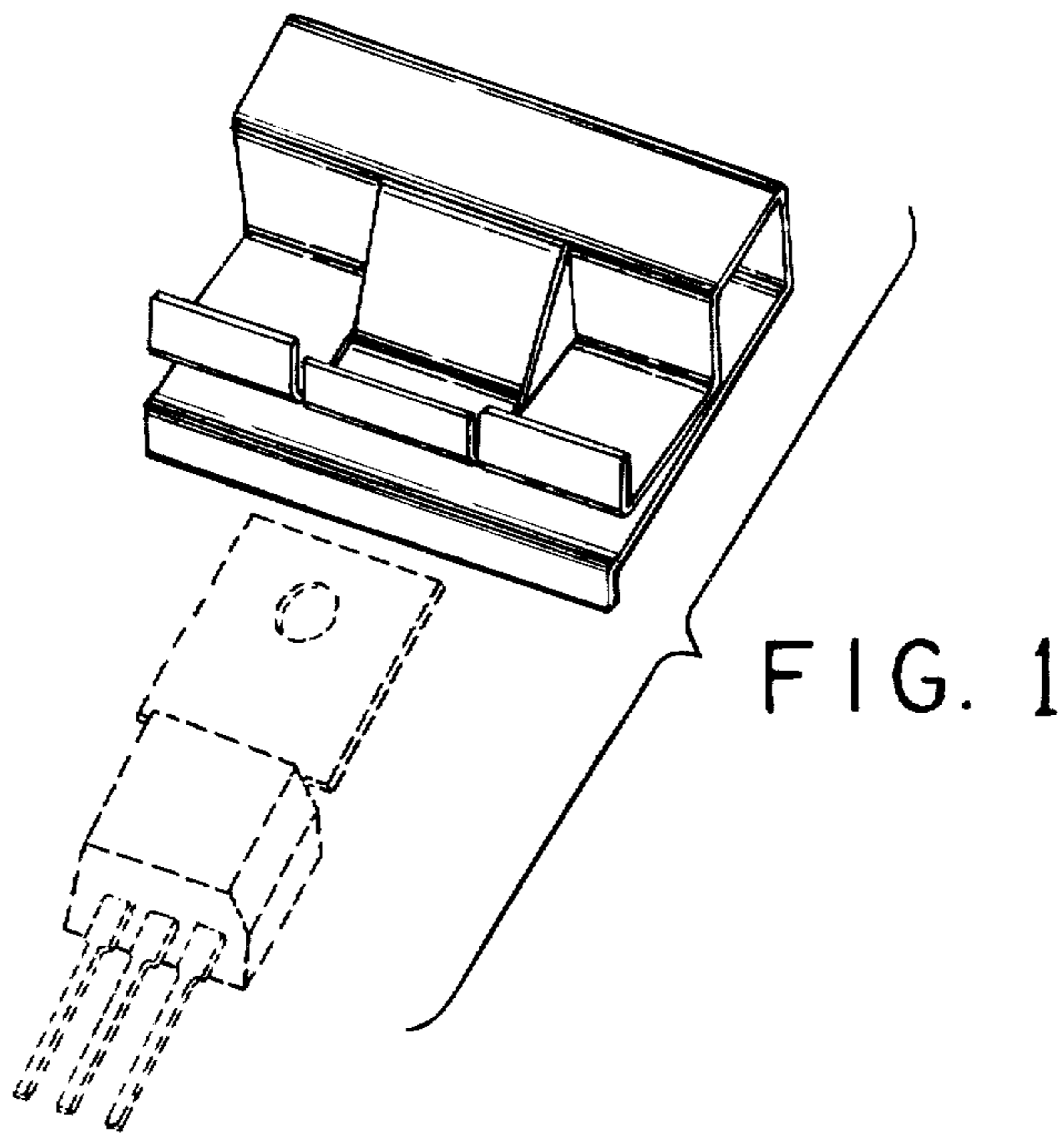


FIG. 2

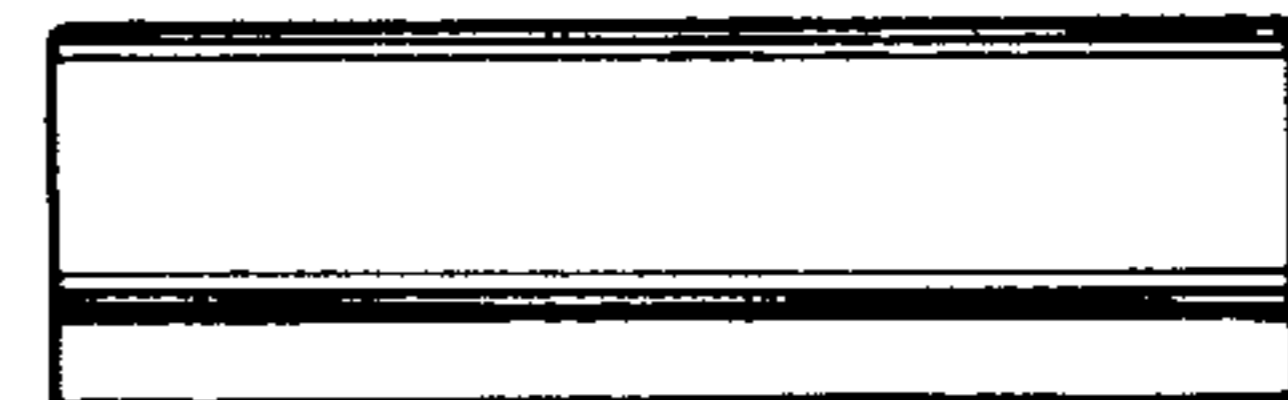


FIG. 3

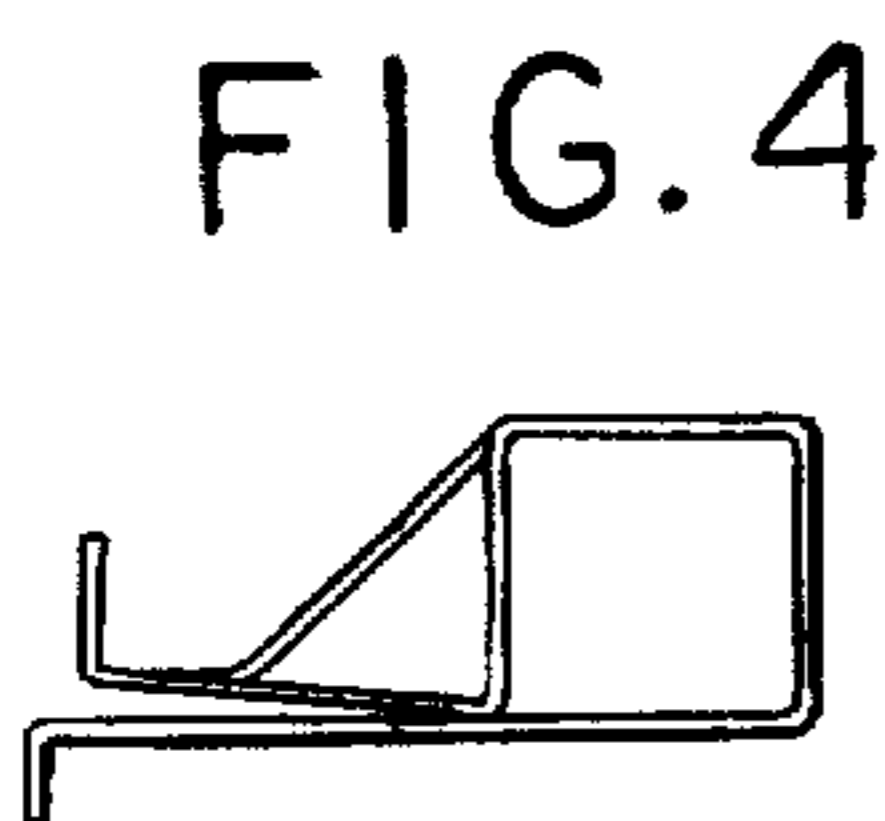


FIG. 4

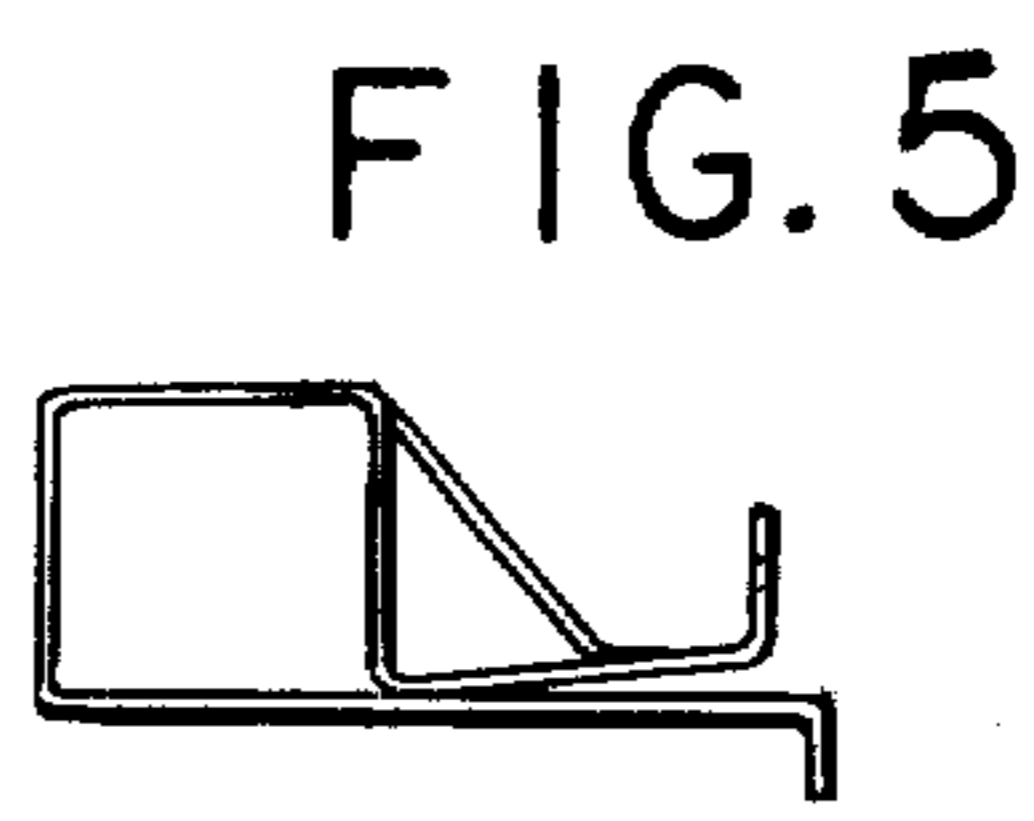


FIG. 5

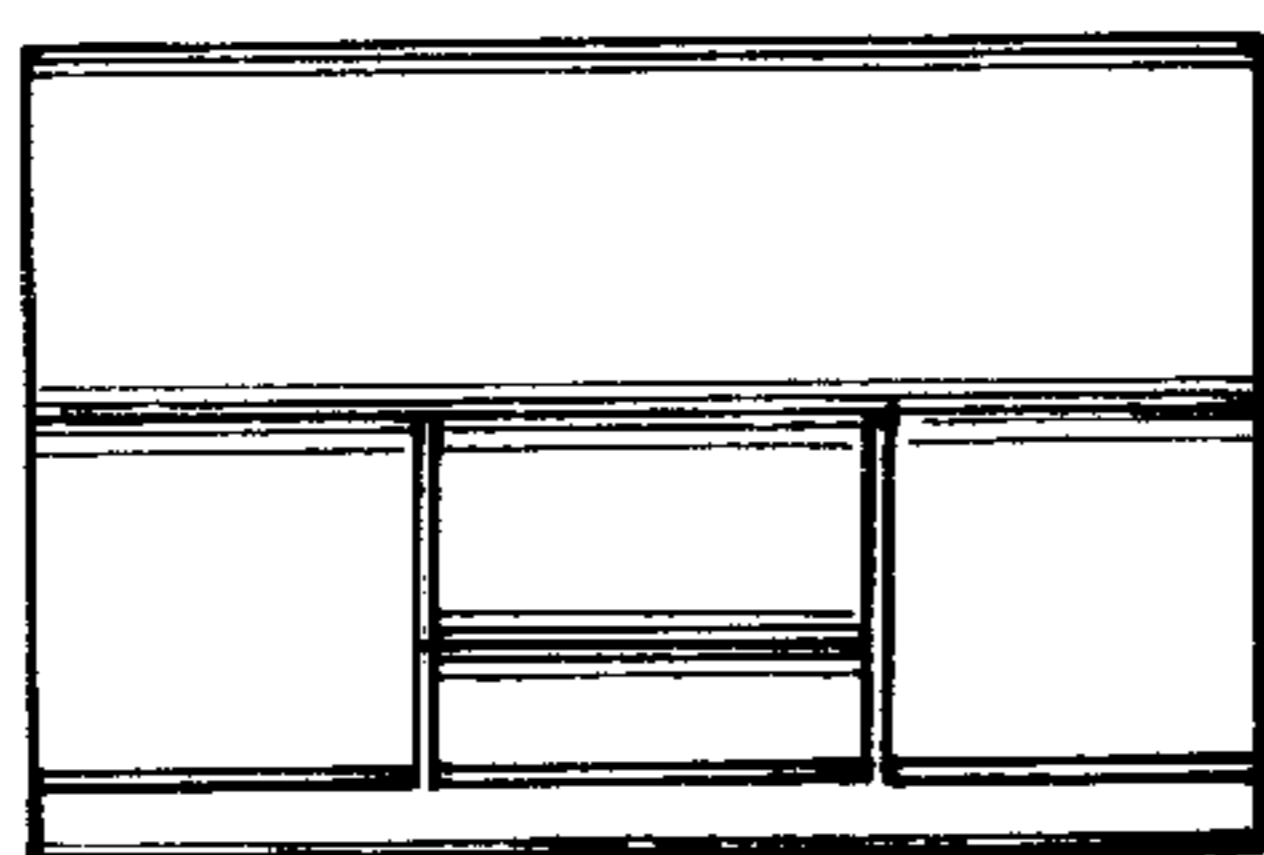


FIG. 6

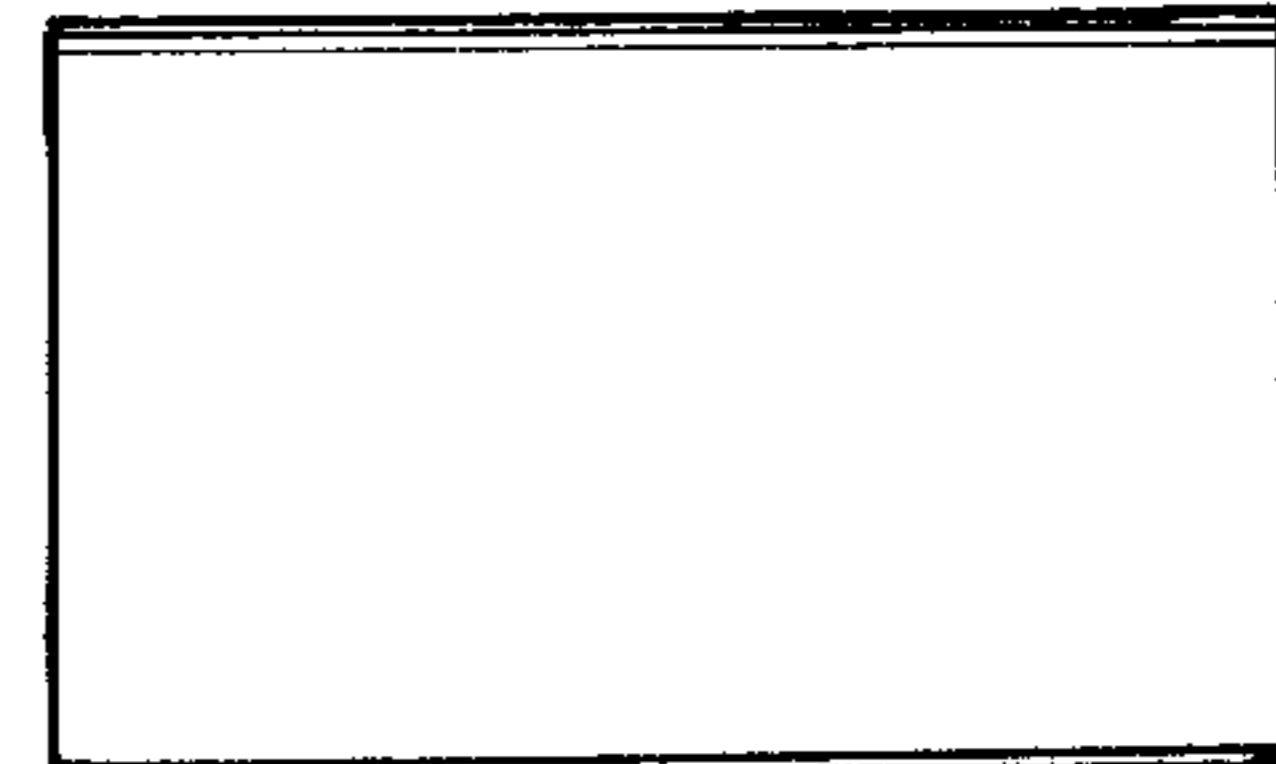


FIG. 7